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B.E. / B.Tech. (Full Time) DEGREE END SEMESTER EXAMINATIONS, APRIL / MAY 2012

PRINTING TECHNOLOGY BRANCH

FOURTH SEMESTER

PT9254 – OFFSET PLATEMAKING

(REGULATIONS 2008)

Time : 3 hrs Max Mark:100

ANSWER ALL QUESTIONS

Part – A (10 x 2 = 20 Marks)

1. What is signature?
2. Write the basic elements of layout?
3. Why we need BoM?
4. Write the features of anyone planning software.
5. Compare the concept of contact angle with wet ability?
6. Draw and explain the inverse square law.
7. Define: adsorption.
8. What is Sensitivity?
9. What is quality control?
10. Write the functions of dotmeter?

Part – B (5 x 16 = 80 Marks)

11. **a.** Discuss characteristics of any 5 equipments and 6 tools used in the offset planning department.

12. **a.** Explain the various methods involved in the step and repeat process.

or

b. Describe the significance steps involved in the preparation of positive and negative film assembly (any one each method).

13. **a.** With the clear flow chart explain the preparation of base plate for an offset process.

or

b. Discuss the various steps involved in the preparation of deep etch plates in detail.

14. **a.** Explain and compare the characteristics features of any two types of Digital imaging plates with diagram.

or

b. i). Write a short note on CTP workflow (4)

ii). Using a neat diagram describe the working principle of External C-t-P system (12).

15. **a.** Explain any eight quality control elements in the GATF colour control bar in detail.

or

b. Describe any five quality control aids used in the standardisation of offset plates in detail.